



# Product Change Notification

**Change Notification #:** 118556-00  
**Change Title:** Select Intel® SSD D5 P5316 Series  
PCN 118556-00, Product Design,  
Firmware Update  
**Date of Publication:** October 18, 2021

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material</b>	January 31, 2022
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## Description of Change to the Customer:

The Intel SKUs listed in the products affected table will have the following changes.

- The firmware version is being updated from ACV10101 to ACV10200.

The changes in the new firmware version are incremental improvements from previous version. Inventory will transition in the Intel factory on or beyond the above date to replace older firmware version with the latest version.

## Customer Impact of Change and Recommended Action:

Since the firmware update has incremental improvement over the previous version, Intel anticipates no product impact with this firmware, and re-qualification is not recommended. Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible. Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

## Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change SA	Post Change SA
Intel® SSD D5 P5316 Series (15.3TB, 2.5in PCIe 4.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPF2NV153TZN1	99AA1N	M35045-100	M35045-101
Intel® SSD D5 P5316 Series (30.7TB, 2.5in PCIe 4.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPF2NV307TZN1	99AA1P	M35043-100	M35043-101
Intel® SSD D5 P5316 Series (15.3TB, EDSFF L 9.5mm PCIe 4.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPFWNV153TZN1	99AA1T	M35055-100	M35055-101
Intel® SSD D5 P5316 Series (30.7TB, EDSFF L 9.5mm PCIe 4.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPFWNV307TZN1	99AA1V	M35054-100	M35054-101

## PCN Revision History:

**Date of Revision:**

October 18, 2021

**Revision Number:**

00

**Reason:**

Originally Published PCN



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## 118556-00

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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